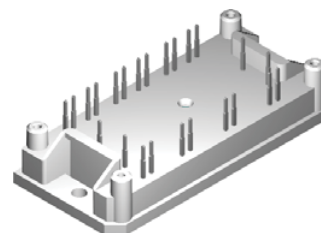
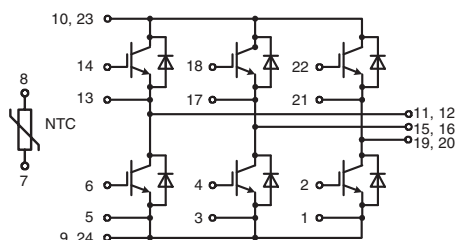


IGBT Module

Sixpack

Square RBSOA

$$\begin{aligned} I_{C25} &= 60 \text{ A} \\ V_{CES} &= 600 \text{ V} \\ V_{CE(sat) \text{ typ.}} &= 2.3 \text{ V} \end{aligned}$$



IGBTs

Symbol	Conditions	Maximum Ratings	
V_{CES}	$T_{VJ} = 25^{\circ}\text{C to } 150^{\circ}\text{C}$	600	V
V_{GES}		± 20	V
I_{C25}	$T_C = 25^{\circ}\text{C}$	60	A
I_{C80}	$T_C = 80^{\circ}\text{C}$	41	A
I_{CM}	$V_{GE} = \pm 15 \text{ V}; R_G = 10 \Omega; T_{VJ} = 125^{\circ}\text{C}$	80	A
V_{CEK}	RBSOA; clamped inductive load; $L = 100 \mu\text{H}$	V_{CES}	
P_{tot}	$T_C = 25^{\circ}\text{C}$	180	W

Symbol	Conditions	Characteristic Values ($T_{VJ} = 25^{\circ}\text{C}$, unless otherwise specified)		
		min.	typ.	max.
$V_{CE(sat)}$	$I_C = 30 \text{ A}; V_{GE} = 15 \text{ V}; T_{VJ} = 25^{\circ}\text{C}$ $T_{VJ} = 125^{\circ}\text{C}$		2.3 2.0	2.8 V
$V_{GE(th)}$	$I_C = 0.25 \text{ mA}; V_{GE} = V_{CE}$	3		5 V
I_{CES}	$V_{CE} = V_{CES}; V_{GE} = 0 \text{ V}; T_{VJ} = 25^{\circ}\text{C}$ $T_{VJ} = 125^{\circ}\text{C}$		1.2	0.2 mA mA
I_{GES}	$V_{CE} = 0 \text{ V}; V_{GE} = \pm 20 \text{ V}$			100 nA
$t_{d(on)}$ t_r $t_{d(off)}$ t_f E_{on} E_{off}	Inductive load, $T_{VJ} = 125^{\circ}\text{C}$ $V_{CE} = 400 \text{ V}; I_C = 30 \text{ A}$ $V_{GE} = \pm 15 \text{ V}; R_G = 3 \Omega$		20 20 130 80 0.6 0.5	ns ns ns ns mJ mJ
C_{ies}			2500	pF
Q_{Gon}			95	nC
R_{thJC} R_{thCH}	(per IGBT)		0.25	0.7 K/W K/W

Features

- IGBTs
 - low saturation voltage
 - fast switching
 - short tail current for optimized performance also in resonant circuits
- HiPerFRED™ diode:
 - fast reverse recovery
 - low operating forward voltage
 - low leakage current
- Industry Standard Package
 - solderable pins for PCB mounting
 - isolated copper base plate
- UL registered E72873

Typical Applications

- AC drives

Diodes

Symbol	Conditions	Maximum Ratings	
I_{F25}	$T_C = 25^\circ\text{C}$	48	A
I_{F80}	$T_C = 80^\circ\text{C}$	33	A

Symbol	Conditions	Characteristic Values		
		min.	typ.	max.
V_F	$I_F = 30\text{ A}; V_{GE} = 0\text{ V}; T_{VJ} = 25^\circ\text{C}$ $T_{VJ} = 125^\circ\text{C}$	2.2	1.7	2.6 V
I_{RM} t_{rr}	$I_F = 30\text{ A}; di_F/dt = -400\text{ A}/\mu\text{s}; T_{VJ} = 100^\circ\text{C}$ $V_R = 300\text{ V}; V_{GE} = 0\text{ V}$	5	65	A ns
R_{thJC} R_{thCH}	(per Diode)	0.3		0.9 K/W K/W

Temperature Sensor NTC

Symbol	Conditions	Characteristic Values		
		min.	typ.	max.
R_{25} $B_{25/85}$	$T = 25^\circ\text{C}$	4.45	4.7	5.0 k Ω K

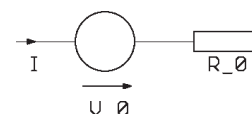
Module

Symbol	Conditions	Maximum Ratings	
T_{VJ}	operating	-40...+125	$^\circ\text{C}$
T_{VJM}		-40...+150	$^\circ\text{C}$
T_{stg}		-40...+125	$^\circ\text{C}$
V_{ISOL}	$I_{ISOL} \leq 1\text{ mA}; 50/60\text{ Hz}$	2500	V~
M_d	Mounting torque (M4)	2.0 - 2.2	Nm

Symbol	Conditions	Characteristic Values		
		min.	typ.	max.
d_s	Creepage distance on surface	12.7		mm
d_A	Strike distance in air	12.7		mm
Weight		40		g

Equivalent Circuits for Simulation

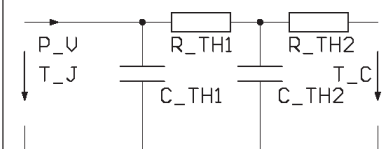
Conduction



IGBT (typ. at $V_{GE} = 15\text{ V}; T_J = 125^\circ\text{C}$)
 $V_0 = 1.1\text{ V}; R_0 = 21.5\text{ m}\Omega$

Free Wheeling Diode (typ. at $T_J = 125^\circ\text{C}$)
 $V_0 = 1.20\text{ V}; R_0 = 19\text{ m}\Omega$

Thermal Response



IGBT (typ.)

$$C_{th1} = tbd\text{ J/K}; R_{th1} = tbd\text{ K/W}$$

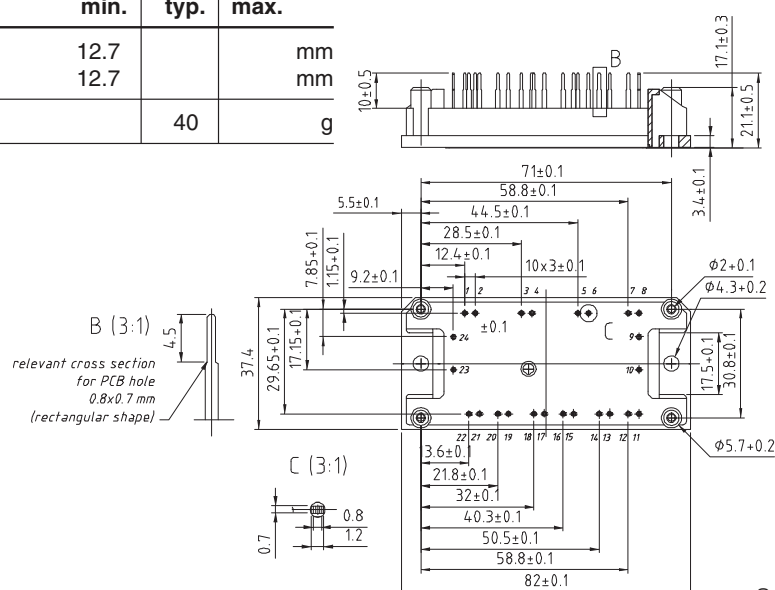
$$C_{th2} = tbd\text{ J/K}; R_{th2} = tbd\text{ K/W}$$

Free Wheeling Diode (typ.)

$$C_{th1} = tbd\text{ J/K}; R_{th1} = tbd\text{ K/W}$$

$$C_{th2} = tbd\text{ J/K}; R_{th2} = tbd\text{ K/W}$$

Dimensions in mm (1 mm = 0.0394")



IXYS reserves the right to change limits, test conditions and dimensions.

© 2005 IXYS All rights reserved